



4/1-25-02
Dade

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: June 27, 2001

For: METHOD FOR FABRICATING A CHIP
SCALE PACKAGE USING WAFER LEVEL
PROCESSING AND DEVICES RESULTING
THEREFROM

Examiner: Unknown

Group Art Unit: 2815

Attorney Docket No.: 3572.1US (97-1243.1)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

October 26, 2001
Date of Deposit

Signature of registered practitioner or other person
having reasonable basis to expect mailing to occur
on date of deposit shown pursuant to 37 C.F.R. §
1.8(a)(1)(ii)

Joseph A. Walkowski
Typed/printed name of person whose signature is
contained above

PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

RECEIVED
JUN 14 2002
TC 2000 MAIL ROOM